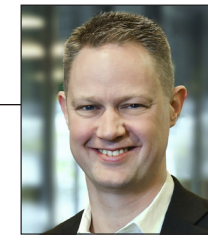
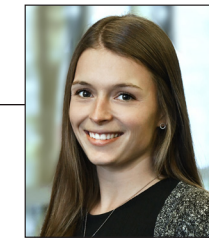
Editorial



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Special issue on Paper Physics highlights continued focus on packaging

It is a great pleasure to present this special issue of *TAPPI Journal*, featuring papers from the 2024 International Paper Physics Conference (IPPC) that have been peer-reviewed for publication in this journal. The conference was held in Wuppertal, Germany, from September 30 to October 2, 2024. This IPPC series is one component of the annual meeting of the International Paper Physics Committee and community, complementing the Fundamental Research Symposia established in 1957—and the Progress in Paper Physics meetings.



The 2024 IPPC in Wuppertal, Germany, had almost 100 attendees from four continents and 13 countries.

The International Paper Physics Committee of TAPPI itself has a long and distinguished history. It was formally established in autumn 1963 and held its first meeting in February 1964. The committee was created to serve as a focal point for research in the physics of paper and fiber networks, bridging the gap between scientific theory and industrial practice. IPPC 2024 once again brought together leading scientists, engineers, and industry professionals to share insights, discuss emerging challenges, and advance the fundamental understanding of paper and fiber-based materials.

Topics in this issue link fundamental with practical

Set against the backdrop of Wuppertal's industrial and academic heritage, the 2024 conference focused on linking fundamental research with practical applications—a theme that resonates throughout the contributions in this issue. As the paper and packaging industries confront new demands for sustainability, performance, and process efficiency, the insights presented at IPPC 2024 highlight the critical role of paper physics in addressing these evolving challenges.

The conference was organized by Professors Jaan-Willem Simon (University of Wuppertal), Markus Biesalski (Technical University of Darmstadt), and Samuel Schabel (Technical University of Darmstadt). The conference was hosted by Professor Jaan-Willem Simon, head of the Chair of Computational Applied Mechanics at the University of Wuppertal. Simon is internationally recognized for his group's pioneering work in constitutive modeling, multiscale simulation, and process optimization of fiber-based materials. Simon was also Chair of the TAPPI International Paper Physics committee at the time of the conference. The 2024 IPPC program can be found here.

The four papers selected for this issue have gone through the *TAPPI Journal* peer-review process, and you will note the common theme of packaging, which has become a major focus for the paper physics community. We believe the readers of this issue will find value in the topics here, which discuss resource-efficient strategies for developing packaging materials, the mechanical response of layered paperboard in 3-D forming, deep drawing, and finite element modeling for the design of corrugated board. Each of these papers reflects the spirit of IPPC: a commitment to deepening our understanding of the physical principles governing fiber-

based materials, while simultaneously developing practical solutions for next-generation paper products.

We extend our sincere appreciation to the authors for their high-quality contributions and to the reviewers for their constructive feedback and support. Special thanks go to the IPPC 2024 organizing committee and the host institutions in Wuppertal for creating an environment that fostered rich dialogue, collaboration, and scientific exchange.

Looking ahead: Worcester College 2026

We hope you enjoy the collection of papers in this issue, and we encourage continued participation in the International Paper Physics community. The next event is the 18th Fundamental Research Symposium to be held at Worcester College in Oxford, UK, September 13-17, 2026. We encourage you to attend this event and potentially submit an extended abstract for consideration. By participating, you can become part of the rich history of research and development in the pulp and paper industry. **TJ**

ABOUT THIS COLUMN

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